EE 330 Quiz #05

Name: Score

Grader:

Briefly answer the following questions:

1. Circle the best conductor: Iron, Copper, Graphene, Aluminum
2. Circle the most widely used metal for wiring in IC: Iron, copper, gold, aluminum
3. Circle the most widely used metal for wire bonding during chip packaging: Iron, copper, gold, aluminum
4. Rank the following layers in conductivity from highest (1) to lowest (5):
	* Gate poly 3
	* P-substrate 5
	* Top metal 1
	* N-well 4
	* Metal 1 2 in sheet resistance, also 1 in rho
5. Rank the area capacitance density from highest (1) to lowest (5)”
	* Ploy to substrate 2
	* Poly to active 1
	* Poly to metal 1 3
	* Top metal to substrate 5
	* Metal 1 to substrate 4